STARPOWER

SEMICONDUCTOR **IGBT**

GD450CLY120P1S

1200V/450A chopper in one-package

General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as electric vehicle and solar power.

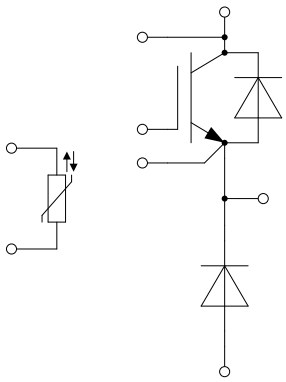
Features

- Low $V_{CE(sat)}$ Trench IGBT technology
- 10μs short circuit capability
- $V_{CE(sat)}$ with positive temperature coefficient
- Maximum junction temperature 175°C
- Low inductance case
- Isolated copper baseplate using DBC technology
- High power and thermal cycling capability

Typical Applications

- High Power Converter
- Solar Power
- Hybrid and Electric Vehicle

Equivalent Circuit Schematic



Absolute Maximum Ratings T_C=25°C unless otherwise noted

IGBT

Symbol	Description	Value	Unit
V_{CES}	Collector-Emitter Voltage	1200	V
V_{GES}	Gate-Emitter Voltage	±20	V
I_C	Collector Current @ T_C=25°C @ T_C=100°C	761 450	A
I_{CM}	Pulsed Collector Current t_p=1ms	900	A
P_D	Maximum Power Dissipation @ T_j=175°C	2.6	kW

Diode

Symbol	Description	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	1200	V
I_F	Diode Continuous Forward Current	450	A
I_{FM}	Diode Maximum Forward Current t_p=1ms	900	A

Module

Symbol	Description	Value	Unit
T_{jmax}	Maximum Junction Temperature	175	°C
T_{jop}	Operating Junction Temperature	-40 to +150	°C
T_{STG}	Storage Temperature Range	-40 to +125	°C
V_{ISO}	Isolation Voltage RMS,f=50Hz,t=1min	2500	V

IGBT Characteristics T_C=25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	I_C=450A,V_{GE}=15V, T_j=25°C		1.70	2.05	V
		I_C=450A,V_{GE}=15V, T_j=125°C		1.95		
		I_C=450A,V_{GE}=15V, T_j=150°C		2.00		
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	I_C=11.3mA,V_{CE}=V_{GE}, T_j=25°C	5.2	6.0	6.8	V
I_{CES}	Collector Cut-Off Current	V_{CE}=V_{CES},V_{GE}=0V, T_j=25°C			1.0	mA
I_{GES}	Gate-Emitter Leakage Current	V_{GE}=V_{GES},V_{CE}=0V, T_j=25°C			400	nA
R_{Gint}	Internal Gate Resistance			2.4		Ω
$t_{d(on)}$	Turn-On Delay Time	V_{CC}=600V,I_C=450A, R_{Gon}=2.5Ω, R_{Goff}=3.1Ω, V_{GE}=±15V, T_j=25°C		235		ns
t_r	Rise Time			96		ns
$t_{d(off)}$	Turn-Off Delay Time			618		ns
t_f	Fall Time			93		ns
E_{on}	Turn-On Switching Loss			44.9		mJ
E_{off}	Turn-Off Switching Loss			41.2		mJ
$t_{d(on)}$	Turn-On Delay Time	V_{CC}=600V,I_C=450A, R_{Gon}=2.5Ω, R_{Goff}=3.1Ω, V_{GE}=±15V, T_j=125°C		268		ns
t_r	Rise Time			107		ns
$t_{d(off)}$	Turn-Off Delay Time			721		ns
t_f	Fall Time			144		ns
E_{on}	Turn-On Switching Loss			63.1		mJ
E_{off}	Turn-Off Switching Loss			53.4		mJ
$t_{d(on)}$	Turn-On Delay Time	V_{CC}=600V,I_C=450A, R_{Gon}=2.5Ω, R_{Goff}=3.1Ω, V_{GE}=±15V, T_j=150°C		278		ns
t_r	Rise Time			107		ns
$t_{d(off)}$	Turn-Off Delay Time			762		ns
t_f	Fall Time			165		ns
E_{on}	Turn-On Switching Loss			68.5		mJ
E_{off}	Turn-Off Switching Loss			60.8		mJ
I_{SC}	SC Data	t_P≤10μs,V_{GE}=15V, T_j=150°C,V_{CC}=800V, V_{CEM}≤1200V		1800		A

Diode Characteristics T_C=25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	I_F=450A,V_{GE}=0V,T_i=25°C		1.65	2.10	V
		I_F=450A,V_{GE}=0V,T_j=125°C		1.65		
		I_F=450A,V_{GE}=0V,T_j=150°C		1.65		
Q_r	Recovered Charge	V_{CC}=600V,I_F=450A, -di/dt=3800A/μs,V_{GE}=-15V, T_j=25°C		38		μC
I_{RM}	Peak Reverse Recovery Current			228		A
E_{rec}	Reverse Recovery Energy			18.1		mJ
Q_r	Recovered Charge	V_{CC}=600V,I_F=450A, -di/dt=3800A/μs,V_{GE}=-15V, T_j=125°C		76		μC
I_{RM}	Peak Reverse Recovery Current			290		A
E_{rec}	Reverse Recovery Energy			31.4		mJ
Q_r	Recovered Charge	V_{CC}=600V,I_F=450A, -di/dt=3800A/μs,V_{GE}=-15V, T_j=150°C		86		μC
I_{RM}	Peak Reverse Recovery Current			318		A
E_{rec}	Reverse Recovery Energy			34.2		mJ

NTC Characteristics T_C=25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
R_{25}	Rated Resistance			5.0		kΩ
ΔR/R	Deviation of R_{100}	T_C=100 °C,R_{100}=493.3Ω	-5		5	%
P_{25}	Power Dissipation				20.0	mW
$B_{25/50}$	B-value	$R_2=R_{25}\exp[B_{25/50}(1/T_2-1/(298.15K))]$		3375		K
$B_{25/80}$	B-value	$R_2=R_{25}\exp[B_{25/80}(1/T_2-1/(298.15K))]$		3411		K
$B_{25/100}$	B-value	$R_2=R_{25}\exp[B_{25/100}(1/T_2-1/(298.15K))]$		3433		K

Module Characteristics T_C=25°C unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Unit
L_{CE}	Stray Inductance		18		nH
$R_{CC'+EE'}$	Module Lead Resistance, Terminal to Chip		0.30		mΩ
R_{thJC}	Junction-to-Case (per IGBT) Junction-to-Case (per Diode)			57.2 101.9	K/kW
R_{thCH}	Case-to-Heatsink (per IGBT) Case-to-Heatsink (per Diode) Case-to-Heatsink (per Module)		9.6 17.0 4.5		K/kW
M	Terminal Connection Torque, Screw M4 Terminal Connection Torque, Screw M8 Mounting Torque, Screw M5	1.8 8.0 3.0		2.1 10 6.0	N.m
G	Weight of Module		825		g

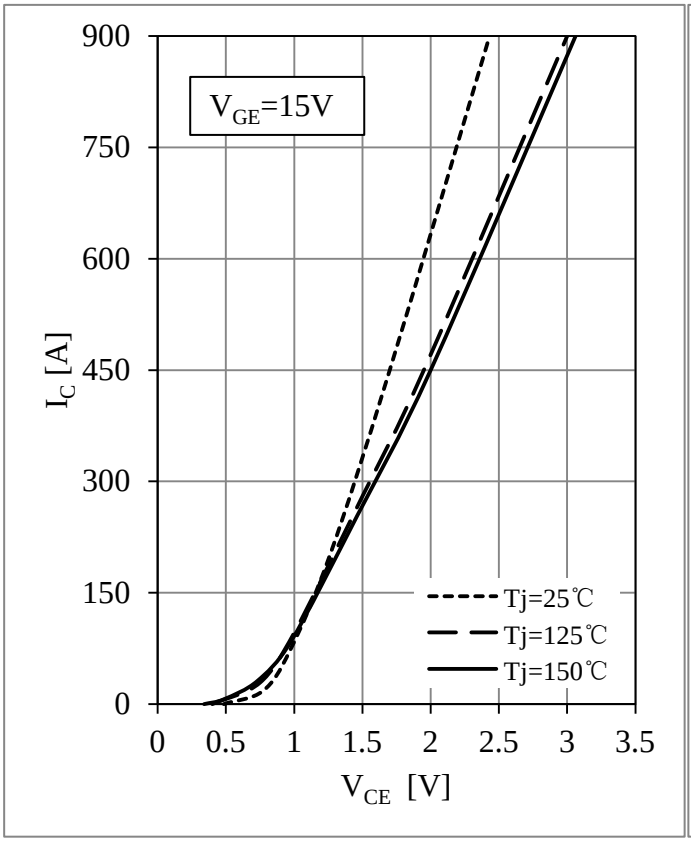


Fig 1. IGBT Output Characteristics

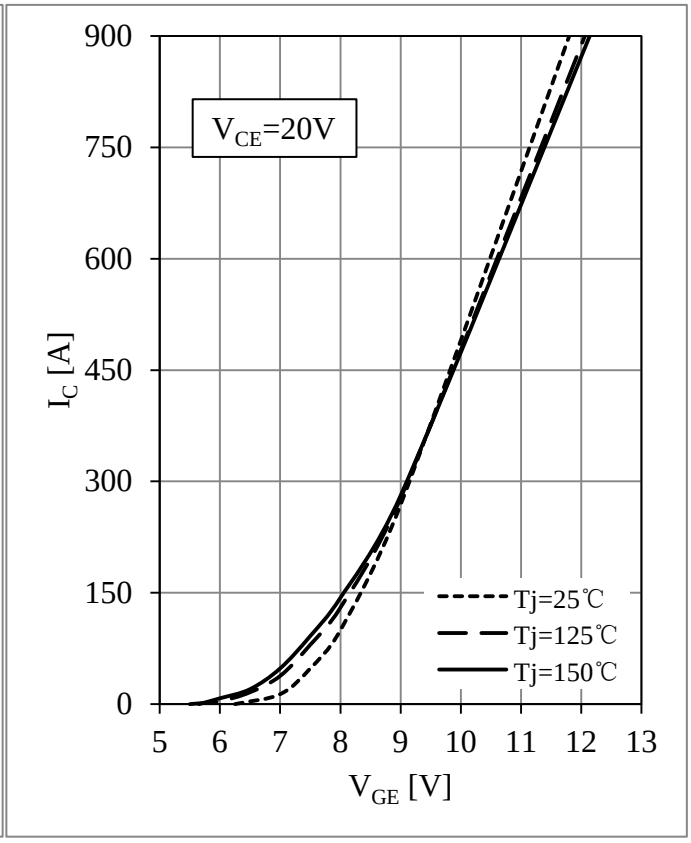


Fig 2. IGBT Transfer Characteristics

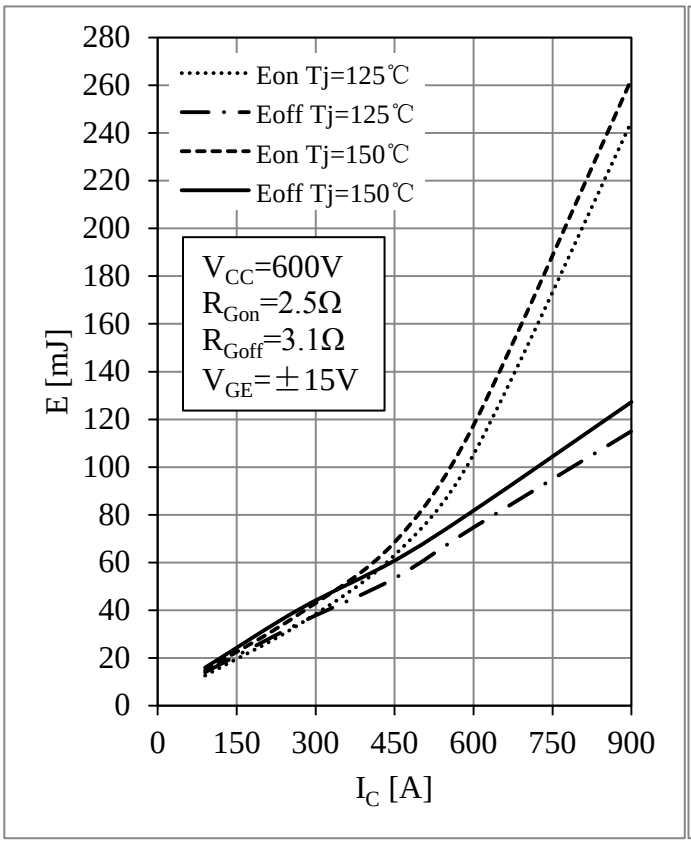


Fig 3. IGBT Switching Loss vs. I_C

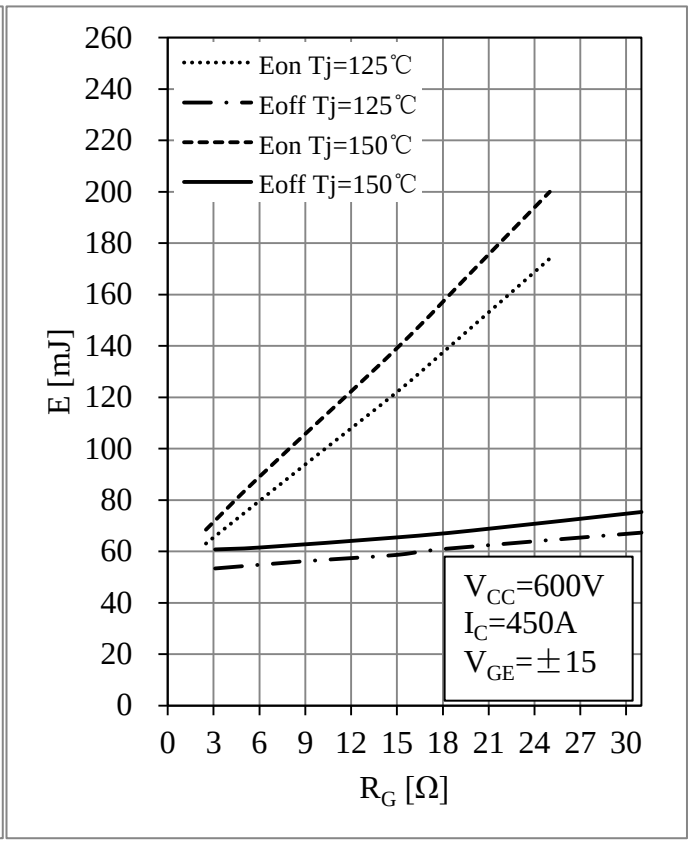


Fig 4. IGBT Switching Loss vs. R_G

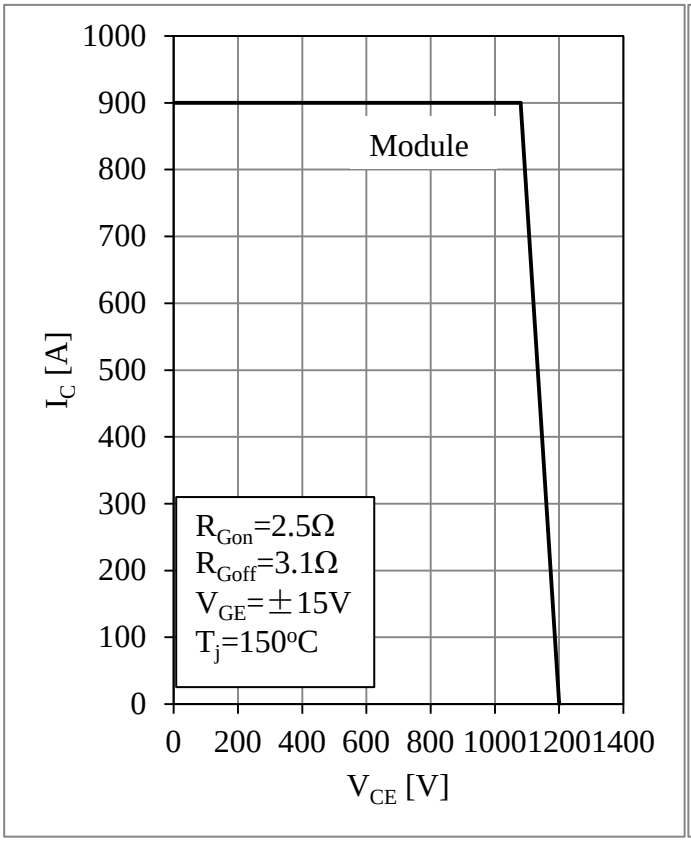


Fig 5. RBSOA

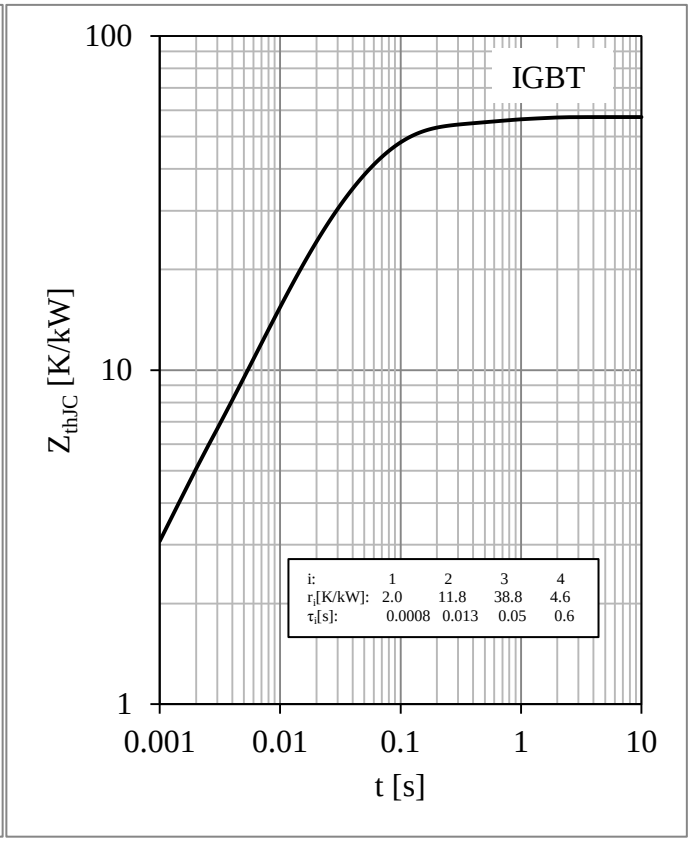


Fig 6. IGBT Transient Thermal Impedance

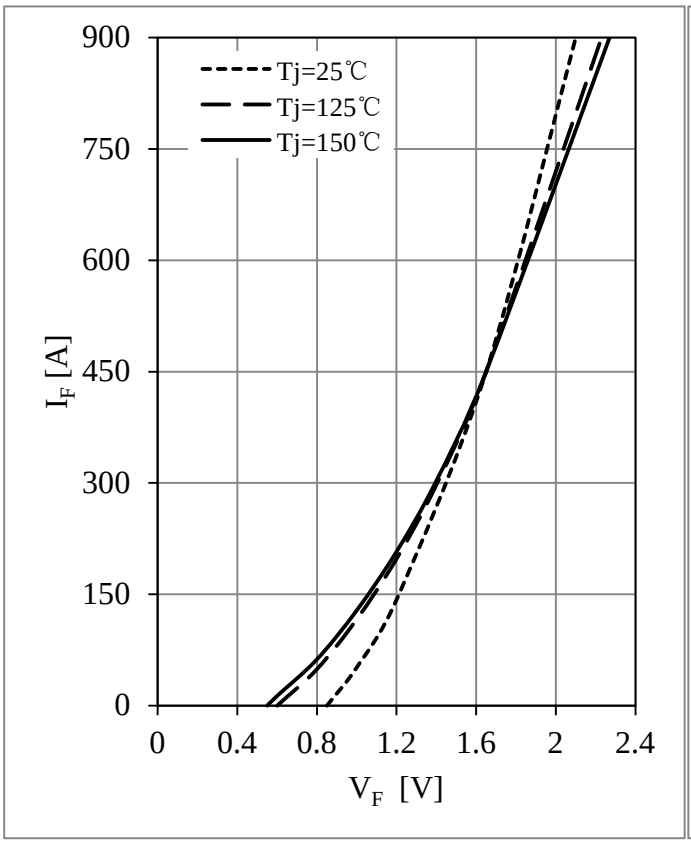


Fig 7. Diode Forward Characteristics

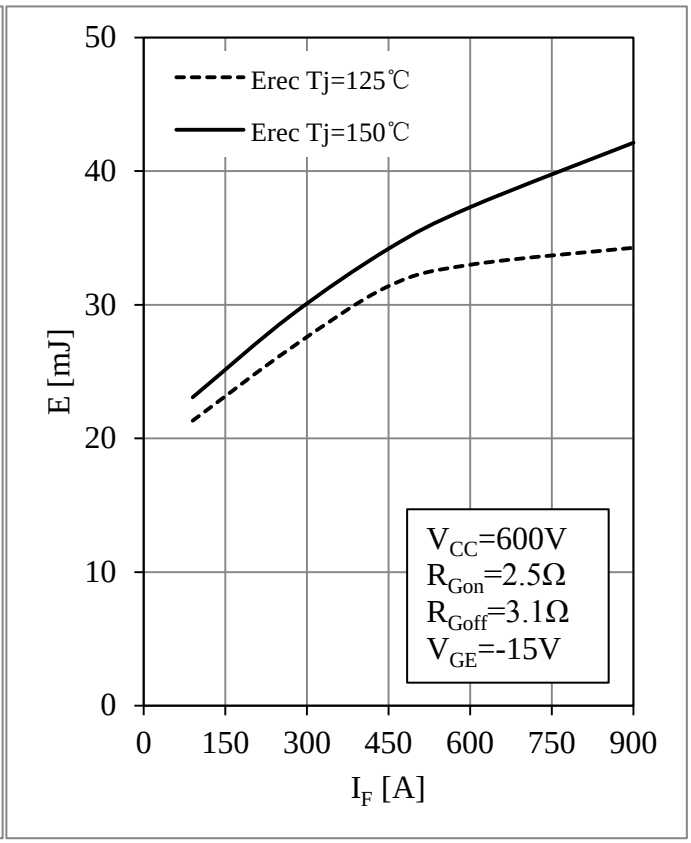


Fig 8. Diode Switching Loss vs. I_F

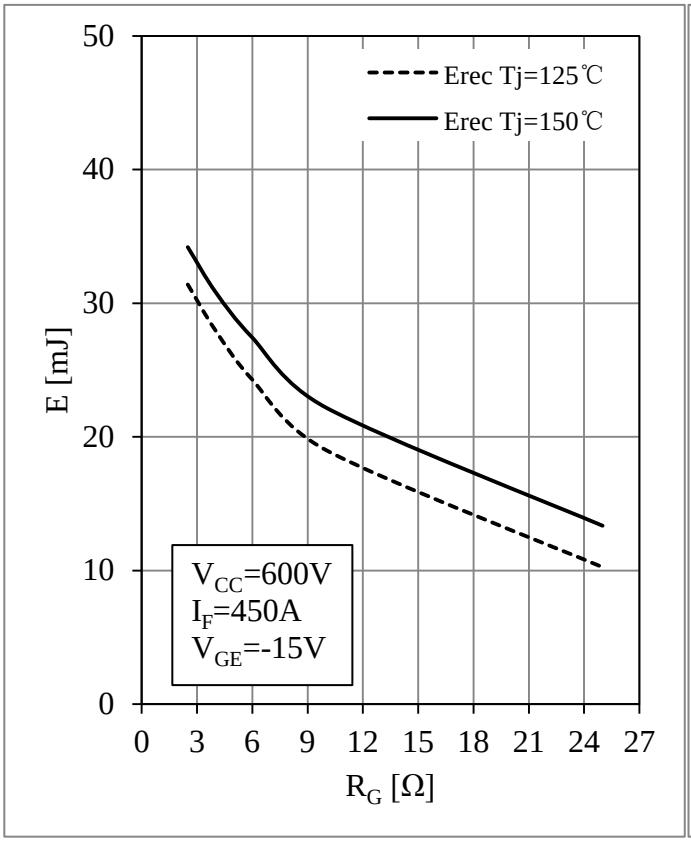


Fig 9. Diode Switching Loss vs. R_G

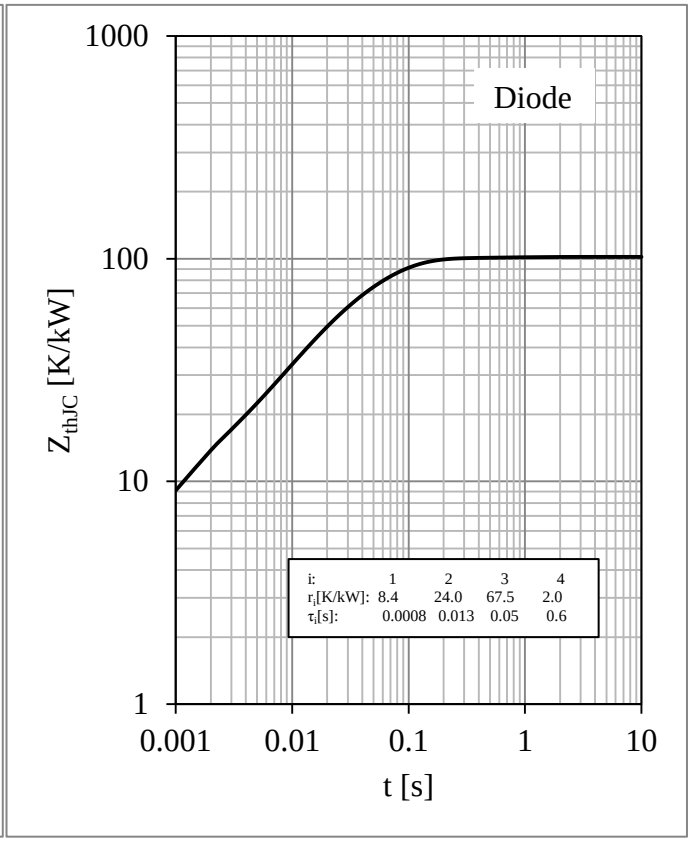


Fig 10. Diode Transient Thermal Impedance

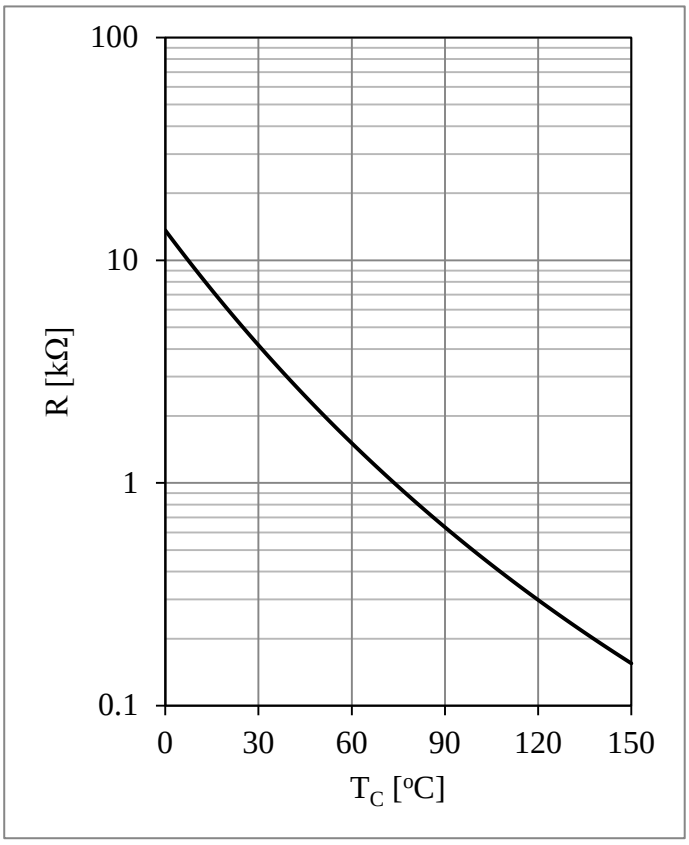
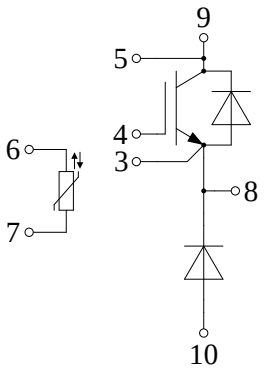


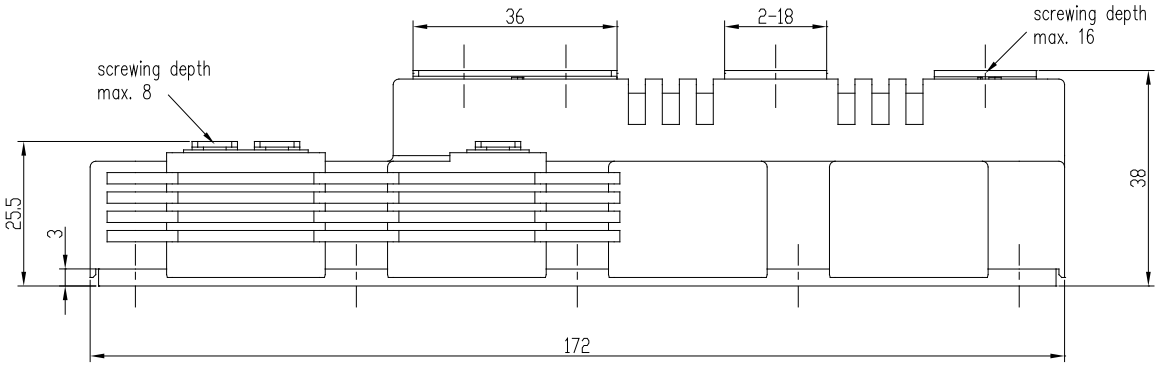
Fig 11. NTC Temperature Characteristic

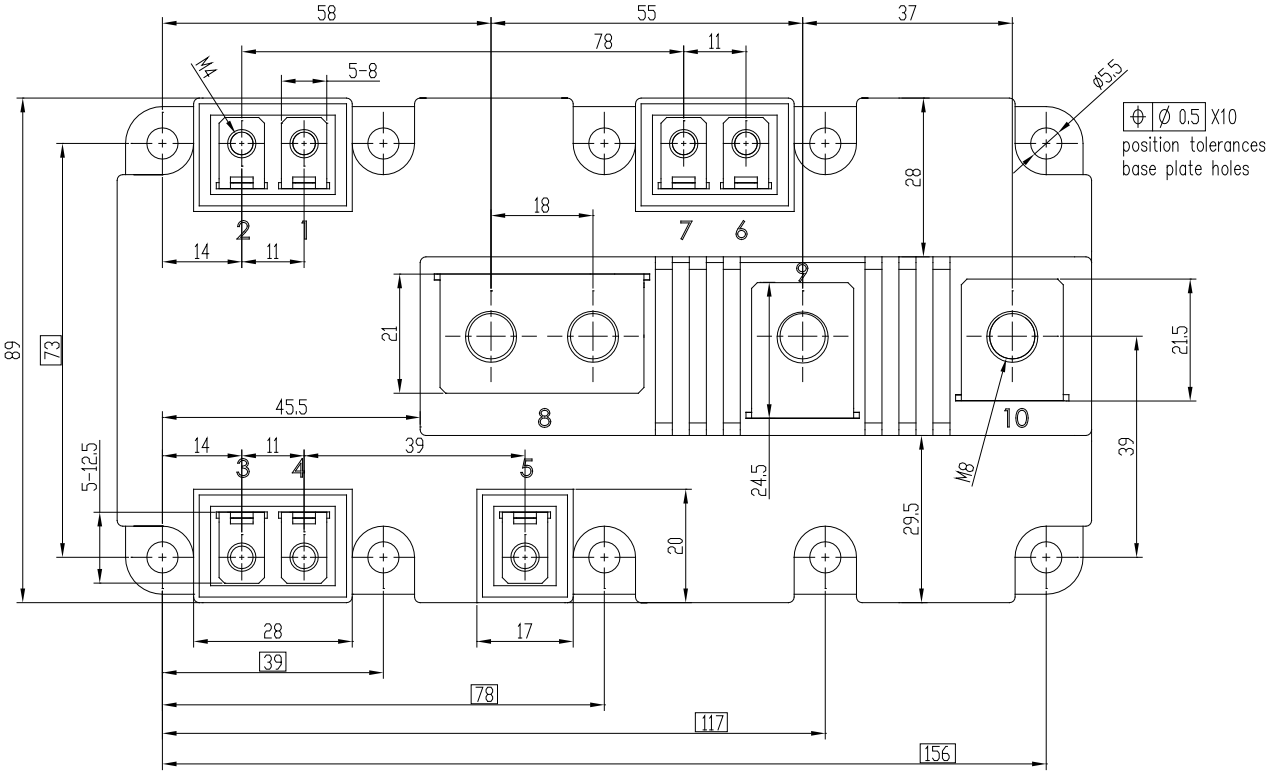
Circuit Schematic



Package Dimensions

Dimensions in Millimeters





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